

Atty. Docket No. CPAC 1017-7  
 Appl. No. 10/632,550

PATENT

This listing of claims will replace all prior versions, and listings, of claims in the application.

### Listing of Claims

1. (currently amended) A multi-package module comprising stacked lower and upper packages, ~~each~~said the lower package including a die attached to and electrically connected to a lower substrate and the upper package including a die attached to and electrically connected to an upper substrate, wherein the upper and lower substrates are interconnected by wire bonding, ~~[[and]]~~ wherein at least one said package comprises a stacked die package, and wherein at least one said stacked die package is encapsulated.
2. (original) The multi-package module of claim 1 wherein the lower package comprises a stacked die package.
3. (original) The multi-package module of claim 1 wherein each of the lower package and the upper package comprises a stacked die package.
4. (original) The multi-package module of claim 1 wherein the upper package comprises a stacked die package.
5. (original) The multi-package module of claim 1 wherein adjacent stacked die in the stacked die package are separated by a spacer.
6. (currently amended) The multi-package module of claim 1, further comprising a heat spreader over the ~~second~~ upper package.
7. (currently amended) A method for making a multi-package module, comprising  
 providing a ~~stacked die~~ first package,  
 providing a second package,  
each said package comprising a die attached to and electrically interconnected to a substrate, at least one of said first package and said second package comprising a stacked die package, wherein at least one said stacked die package is encapsulated.

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stacking the second package over the first package, and  
forming electrical interconnects between the first package and the second package by wire bonding.

8. (currently amended) The method of claim 7 wherein providing said package comprising a stacked die ~~[[first]]~~ package comprises testing stacked die packages for a performance and reliability requirement, and identifying a package that meets the requirement as a said ~~[[first]]~~ stacked die package.

9. (original) The method of claim 7 wherein providing a second package comprises testing packages for a performance and reliability requirement, and identifying a package that meets the requirement as a said second package.

10. (currently amended) The method of claim 7 wherein providing said package comprising a stacked die ~~[[first]]~~ package comprises providing an unsingulated strip of stacked die packages.

11. (currently amended) The method of claim 7 wherein providing said package comprising a stacked die ~~[[first]]~~ package comprises providing a package comprising a first die affixed to a ~~[[first]]~~ package substrate, a second die affixed over the first die, and wire bond interconnects between said first and second die and said substrate.

12. (currently amended) The method of claim 11 wherein providing said package comprising a stacked die ~~[[first]]~~ package comprises providing a package further comprising a spacer interposed between said first and said second die.

13. (original) The method of claim 7, further comprising providing a heat spreader.

14. (original) The method of claim 7, further comprising attaching second-level interconnect balls onto the first package substrate.

15. (original) The method of claim 7, further comprising encapsulating the stacked packages on the module in a molding compound.

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16. (original) A mobile device comprising the multi-package module of claim 1.
17. (original) A computer comprising the multi-package module of claim 1.